Be sure this is the latest version!

NOTE 5c

SEC A–A
(not to scale)

PCB

DISPLAY

.04
.08

4.425

r=0.625
typ. 6 pl.

0.85

DISPLAY UNIT

1.340

A

A

NOTE 5a

0

0

NOTE 4

0.910

0.540

0.710

0.625 typ

0.375 typ

0.565

0.69

0.625 typ

1.860

2.61

3.535

NOTES:

1: DESCRIPTION:

.062" (nominal) Etched Circuit board, 2 side 1 oz (finished) Cu, for hybrid SMT/through lead. Minimum 8/8 SMT design rules. Not for lead free assembly.

2: MATERIAL & FINISH:

Refer to 00–PCB–README file for solder mask & silkscreen colors and quantities.

3. Dimensions:

Finish dimensions per drawing. +/– .005" (.000 decimal), +/– .015" (.00 decimal), +/– .003" on holes, 1/64" on fractions, unless noted. Undimensioned holes to be positioned per artwork.

4. Co–ordinate System:

Drill file and SMT centroid 0, 0 origin (reference point) located per drawing.

5. ASSEMBLY (refer also to 00–ASM–README file).

a. DS2 mounts "lens down" on SMD side. Verify presence of hole, and fit of DS2 prior to assembly.
b. Place RED pushbuttons at S1 and S2 ONLY. Place BLACK pushbuttons at S3–S7.
c. Fixture display to maintain display – PCB clearance per drawing.
b. Orient battery holders per legend.

LAYER STACK UP DETAIL
SMD COMPONENT Side

TOP SILK [thotcon_0x5–F_SilkS.gto]	
TOP SOLDER MASK [thotcon_0x5–F_Mask.gts]	
TOP COPPER [thotcon_0x5–F_copper.gtl]	
CORE/DIELECTRIC	
BOTTOM COPPER [thotcon_0x5–B_copper.gbl]	
BOTTOM SOLDER MASK [thotcon_0x5–B_mask.gbs]	
BOTTOM SILK [thotcon_0x5–B_SilkS.gbo]	

0.062 +/– 10%

THROUGH–HOLE COMPONENT Side

SEE ALSO thotcon_0x5–F_Paste.gtp (top paste), thotcon_0x5–B_Paste.gbp (bottom paste)